	Туре	L#	Hits	Search Text	DBs	ne Stamp	Comments
1	BRS	L1	29627	(wafer\$1 or substrate\$1 or cassette\$1) with (vacuum)	USPAT	2001/12/17 09:33	
2	BRS	L2	11742	1 and ((vacuum) near2 (process\$3 or chamber\$1))	USPAT	2001/12/17 09:35	
3	BRS	L3	238	2 and ((convev\$3) with (transfer\$3))	USPAT	2001/12/17 09:37	

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	U	1	Document ID	sue Date	Pages	Title	Current OR
1			US 6320154 B1	20011120	16	Plasma processing method	219/121.41
2	⊠		US 6319322 B1	20011120	29	Substrate processing apparatus	118/666
3	☒		US 6314658 B1	20011113	11	Vacuum processing apparatus and operating method therefor	34/406
4	⊠		US 6306267 B1	20011023	18	1 A - Al J - C J	204/192.25
5	⊠		US 6301802 B1	20011016	9	Vacuum processing apparatus and operating method therefor	34/406
6	⊠		US 6301801 B1	20011016	8	Vacuum processing apparatus and operating method therefor	34/406
7	⋈		US 6294038 B1	20010925	13	Apparatus and method for applying linerless labels	156/238
8	⋈		US 6286230 B1	20010911	22	Method of controlling gas flow in a substrate processing system	34/403
9	⊠		US 6285102 B1	20010904	20	Drive mechanism having a gas bearing operable under a negative pressure	310/90
10	⊠		US 6284173 B1	20010904	10	Method for vacuum encapsulation of semiconductor chip packages	264/102
11	⊠		US 6283693 B1	20010904	12	Method and apparatus for semiconductor chip handling	414/403
12	⊠		US 6271503 B1	20010807	5	Dimensional compensating vacuum fixture	219/444.1
13			US 6265242 B1	20010724	34	Solar cell module and a process for producing said solar cell module	438/66
14	☒		US 6263588 B1	20010724	8	Vacuum processing apparatus and operating method therefor	34/417
15	Ø		US 6260898 B1	20010717	10	Mounting head for electronic component-mounting apparatus	294/64.1
16	⋈		US 6258690 B1	20010710	15	Method of manufacturing semiconductor device	438/396
17	⊠		US 6254809 B1	20010703	72	System and method for curing a resin disposed between a top and bottom substrate with thermal management	264/1.33
18	⊠		US 6248399 B1	20010619	192	Industrial vapor conveyance and deposition	427/248.1

	0 VD-6	Retrie lassif	I Inventor	16			-	4	E
	Current XRef	Retrievellassif	Inventor Akabasi Takashi	S	P	2	3	4	5
1	118/723I ; 438/715		Akahori, Takashi , et al.	⊠					
2	118/319 ; 118/320 ; 118/58 ; 118/667 ; 118/712		Ueda, Issei , et al.						
3	134/902 ; 34/92		Kato, Shigekazu , et al.						
4	204/192.12		Tamura, Hideo . et al.						
5	118/729 ; 34/229 ; 34/417 ; 34/92 ; 414/744.1 ; 414/744.6 ; 414/939 ; 414/940		Kato, Shigekazu , et al.						
6	34/228 ; 34/92		Kato, Shigekazu , et al.						
7	156/302 ; 156/541 ; 427/146		Majkrzak, Gerald A.						
8	34/410 ; 34/412 ; 414/217 ; 414/220 ; 414/939		White, John M. , et al.						
9	310/12 ; 34/92 ; 384/12 ; 414/676		Matsuoka, Takaaki , et al.						
10	264/272.15 ; 264/272.17 ; 425/546 ; 425/812		Austin, Eric , et al.						
11 11	156/344 ; 414/416.06 ; 414/416.1 ; 438/464		Acello, Salvatore , et al.						
12	118/724 ; 269/21		Hall, Richard Ronald , et al.						
13	136/244 ; 136/246 ; 136/251 ; 136/252 ; 136/290 ; 136/291 ; 257/428 ; 257/431 ; 257/464 ; 438/67 ; 438/67 ; 438/70 ; 438/72 ; 438/73 ; 438/80		Komori, Ayako , et al. Kato, Shigekazu						
14	34/229		, et al.						
15	29/740 ; 29/743		Kano, Yoshinori , et al.						
16	438/253 ; 438/769 ; 438/775 ; 438/791 ; 438/908		Zenke, Masanobu						
17	156/275.5 ; 156/275.7 ; 156/379.8 ; 264/1.38 ; 425/174.4 ; 425/810		Parent, Scott R. , et al.						
18	137/561A ; 427/255.5 ; 95/45 ; 96/4		Hehmann, Franz						

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\vdash	U	1	Document ID	sue Date	Pages	Title	Current OR
19	⊠		US 6245202 B1	20010612	15	Plasma treatment device	204/298.06
20	Ø		US 6245189 B1	20010612	24	High Throughput plasma treatment system	156/345
21	⊠		US 6244812 B1	20010612	13	Low profile automated pod door removal system	
22	×		US 6241824 B1	20010605	8	Apparatus for the coating of substrates in a vacuum chamber	118/730
23	☒		US 6238161 B1	20010529	11	Cost effective modular-linear wafer processing	414/217
24	⊠		US 6235634 B1	20010522	28	Modular substrate processing system	438/680
25	⊠		US 6234107 B1	20010522	12	Auxiliary vacuum chamber and vacuum processing unit using same	118/723R
26	⊠	Ο.	US 6231732 B1	20010515	28	Cylindrical carriage sputtering system	204/298.26
27	☒		US 6227436 B1	20010508		Method of fabricating an electronic circuit device and apparatus for	228/180.22
28	☒		US 6224679 B1	20010501 ·		performing the method Controlling gas in a multichamber processing system	118/719
29	☒		US 6215897 B1	20010410		Automated substrate processing system	382/151
30	⊠		US 6214412 B1	20010410		System and method for distributing a resin disposed between a top substrate and a bottom substrate	427/240
31			US 6206071 B1	20010327		Apparatus and method for applying linerless labels	156/519
32	⊠		US 6196154 B1	20010306		Air lock for introducing substrates to and/or removing them from a treatment chamber	118/723VE
33	Ø		US 6193507 B1	20010227		Multi-function chamber for a substrate processing system	432/247
34	⊠		US 6190104 B1	20010220		Treatment object conveyor apparatus, semiconductor manufacturing apparatus, and treatment object treatment method	414/217
35	Ø		US 6186722 B1	20010213		Chamber apparatus for processing semiconductor devices	414/217

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	Current XRef 118/723AN	Retrie classif	Inventor	S	P	2	3_	4	5
19	; 118/723I ; 118/723IR ; 156/345 ; 204/298.11		Edamura, Manabu , et al.						
20	118/723E ; 118/723R ; 118/729		Rigali, Louis A. , et al.						
21	118/719 ; 414/217.1 ; 414/684.3 ; 414/937 ; 414/939		Patterson, Jesse , et al.						
22	118/500 ; 118/503 ; 118/719 ; 118/729 ; 204/298.25 ; 204/298.26 ; 204/298.28		Brauer, Gunter , et al.						
23	414/939		Kirkpatrick, Thomas I. , et al.						
24	118/715 ; 118/719 ; 118/725 ; 118/728 ; 204/192.12 ; 204/298.25 ; 204/298.35 ; 414/217		White, John M. , et al.						
25	118/719 ; 118/728 ; 156/345		Tanaka, Keiichi , et al.						
26	118/503 ; 118/58 ; 118/69 ; 118/719 ; 204/298.09 ; 204/298.15 ; 204/298.23 ; 204/298.25 ; 204/298.28		Hollars, Dennis R. , et al.						
27	219/121.68 ; 228/205 ; 228/219		Nishikawa, Toru , et al.						
28	156/345 ; 414/935		Sasaki, Yoshiaki . et al.						
29	348/87 ; 382/149		Beer, Emanuel , et al.						
30	118/52 ; 118/56 ; 156/285 ; 156/74 ; 369/286		Paulus, Joseph W. , et al.						
31	156/265 ; 156/270 ; 156/302 ; 156/521 ; 156/541 ; 156/542		Majkrzak, Gerald A. , et al.						
32	118/718 ; 118/719 ; 204/298.25 ; 222/367 ; 222/368 ; 414/217 ; 414/219 ; 414/220		Baumecker, Tomas , et al.						
33	118/724 ; 118/725 ; 414/222.11 ; 432/184		White, John M. , et al.						
34	414/939		lkeda, Kazuhito , et al.						
35	118/719 ; 414/935 ; 414/939		Shirai, Hidenobu						

							
	٦	1	Document ID	ue Date	Pages	Title	Current OR
36	⊠		US 6183523 B1	20010206		Apparatus for thermal control of variously sized articles in vacuum	29/25.01
37	⊠		US 6183186 B1	20010206		Wafer handling system and method	414/416.03
38	☒		US 6179923 B1	20010130		Deposition apparatus for an organic thin-film light-emitting element	118/719
39	☒		US 6174366 B1	20010116		Apparatus and method for processing of semiconductors, such as silicon chips	117/84
40	⊠		US 6173948 B1	20010116	•	Dimensional compensating vacuum fixture	269/21
41	⊠		US 6169324 B1	20010102		Semiconductor integrated circuit device, process for fabricating the same,	257/678
42	Ø		US 6165885 A	20001226		Method of making components with solder balls	438/612
43	Ø		US 6159868 A	20001212		Method of forming a high quality layer of BST	438/778
44	Ø		US 6143081 A	20001107		Film forming apparatus and method, and film modifying apparatus and method	118/719
45	⊠		US 6138745 A	20001031		Two-stage sealing system for thermally conductive chuck	165/80.1
46			US 6132562 A	20001017		Method and device for transporting cylindrical substrates to be coated	204/192.12
47	×		US 6130171 A	20001010		Residue removal process for forming inter-level insulating layer of paraylene polymer without peeling	438/781
48	⊠		US 6127255 A	20001003		Semiconductor integrated circuit device, process for fabricating the same, and apparatus for fabricating the same	438/624

	Current XRef	Retrie	Inventor	S	P	2	3	4	5
-	118/725	Kettle	Hurwitt, Steven						
36	; 118/728 ; 250/398		, et al.						
37	414/222.01 ; 414/749.1 ; 414/937 ; 414/940	***	Howells, John , et al.						
38	118/726		Yamamoto, Tetsuya , et al.						
39	118/719 ; 118/729 ; 156/345 ; 427/255.5 ; 427/255.7 ; 438/706 ; 438/716 ; 438/719		Ihantola, Heikki						
40	165/80.5		Hall, Richard Ronald , et al.						
41	257/213 ; 438/106		Sugiura, Jun , et al.						
42	257/737 ; 257/738 ; 438/613 ; 438/614 ; 438/615 ; 438/616		Gaynes, Michael Anthony , et al.						
43			Hieda, Katsuhiko , et al.						
44	118/715 ; 118/722 ; 118/723IR ; 118/723ME ; 118/725		Shinriki, [/] liroshi , et al.						
45	118/728 ; 156/345 ; 165/80.2		Moslehi, Mehrdad M.						
46	118/715 ; 118/720 ; 118/723R ; 118/723VE ; 118/728 ; 118/729 ; 118/730 ; 118/731 ; 204/192.1 ; 204/192.15 ; 204/192.23 ; 204/298.02 ; 204/298.23 ; 204/298.25 ; 204/298.25 ; 204/298.26 ; 204/298.27 ; 204/298.27 ; 204/298.28 ; 427/255.5 ; 427/471 ; 427/481 ; 427/569 ; 427/578		Baumecker, Tomas , et al.						
47	438/778 ; 438/780		Gomi, Hideki						
48	438/622 ; 438/631 ; 438/668 ; 438/688 ; 438/780 ; 438/787 ; 438/791		Sugiura, Jun , et al.						

	U	1	Document ID	ue Date	Pages	Title	Current OR
49	×		US 6126790 A	20001003		Method of magnetically orienting thin magnetic films with a multiple-coil electromagnet	204/192.1
50	Ø		US 6119895 A	20000919		Method and apparatus for dispensing materials in a vacuum	222/1
51	⊠		US 6112431 A	20000905		Vacuum processing and operating method	34/406
52	×		US 6111225 A	20000829		Wafer processing apparatus with a processing vessel, upper and lower separately sealed heating vessels, and means for maintaining the	219/390
53	☒		US 6108929 A	20000829		vessels at predetermined pressures Vacuum processing apparatus	34/92
54			US 6106657 A	20000822		System and method for dispensing a resin between substrates of a bonded storage disk	156/295
55	⊠		US 6103039 A	20000815		System and method for thermally manipulating a combination of a top and bottom substrate before a curing operation	156/223
56	⊠		US 6101707 A	20000815		Mounting head for electronic component-mounting apparatus	29/740
57	⊠		US 6098272 A	20000808		System for maintaining concentricity of a combination of a top and bottom substrate during the assembly of a bonded storage disk	29/701
58	⊠		US 6096133 A	20000801		Chemical vapor deposition apparatus	118/712
59	Ø		US 6095085 A	20000801		Photo-assisted remote plasma apparatus and method	118/723MP
60	⊠		US 6093290 A	20000725		Method of generating a reciprocating plurality of magnetic fluxes on a	204/192.12
61	⊠		US 6086362 A	20000711		target Multi-function chamber for a substrate processing system	432/243
62	⊠		US 6073576 A	20000613		Substrate edge seal and clamp for low-pressure processing equipment	118/723E
63	⊠		US 6070341 A	20000606		Vacuum processing and operating method with wafers, substrates and/or semiconductors	34/406

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49	118/723FE ; 118/723FI ; 204/192.11 ; 204/192.12 ; 204/192.13 ; 204/192.16 ; 204/298.02 ; 204/298.03 ; 204/298.09 ; 204/298.17 ; 204/298.19 ; 335/209 ; 335/213 ; 335/282 ; 335/297 ; 335/297 ; 335/306 ; 427/571 ; 427/598		Moslehi, Mehrdad M. , et al.						
50	222/152 ; 222/333 ; 222/415		Fugere, Jeffrey P. , et al.						
51			Kato, Shigekazu , et al.						
52	118/724 ; 118/725 ; 219/411		Ohkase, Wataru , et al.						
53			Kato, Shigekazu , et al.						
54	118/44 ; 118/56 ; 156/275.5 ; 156/275.7 ; 156/578 ; 156/87 ; 369/286 ; 369/287		Rossignol, Brian C. , et al.						
55	156/222 ; 156/273.3 ; 156/273.5 ; 156/275.5 ; 156/275.7 ; 156/282 ; 156/497 ; 156/498 ; 156/74 ; 369/286		Paulus, Joseph W. , et al.						
56	29/742 ; 29/743		Kano, Yoshinori , et al.						
57	156/556 ; 269/49 ; 269/52 ; 29/271 ; 29/466 ; 33/644		Paulus, Joseph W. , et al.						
58	118/708 ; 118/724 ; 118/726		Yuuki, Akimasa , et al.						
59	118/723ER ; 118/723IR ; 156/345		Agarwal, Vishnu K.						
60	204/192.13 ; 204/298.2 ; 204/298.23 ; 204/298.24		Tamura, Hideo , et al.						
61	118/724 ; 118/725 ; 432/247		White, John M. , et al.						
62	118/52 ; 118/728 ; 156/285 ; 156/345 ; 438/618		Moslehi, Mehrdad M. , et al.						
63			Kato, Shigekazu , et al.						

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64	Ø		US 6055740 A	20000502		Vacuum processing apparatus and operating method therefor	34/92
65	⊠		US 6053687 A	20000425		Cost effective modular-linear wafer processing	414/222.13
66	⊠		US 6045315 A	20000404		Robot apparatus and treating apparatus	414/217
67	⊠		US 6044576 A	20000404		Vacuum processing and operating method using a vacuum chamber	34/406
68	Ø		US 6042707 A	20000328		Multiple-coil electromagnet for magnetically orienting thin films	204/298.16
69	⊠		US 6033732 A	20000307		Apparatus for and method of forming thin film by chemical vapor deposition	427/255.29
70	⊠		US 6033475 A	20000307		Resist processing apparatus	118/320
71	Ø		US 6023068 A	20000208		Somiconductor device manufacturing apparatus	250/402 2
		<u> </u>				Semiconductor device manufacturing apparatus	250/492.2
72	⊠		US 6022418 A	20000208		Vacuum processing method	118/728
73	⊠		US 6021737 A	20000208		lon plating apparatus that prevents wasteful consumption of evaporation	118/723E
74	⊠		US 6016611 A	20000125		material Gas flow control in a substrate processing system	34/92
75	☒		US 6012235 A	20000111		Vacuum processing apparatus and operating method therefor	34/406
76	⊠		US 6011825 A	20000104		Production of .sup.64 Cu and other radionuclides using a charged-particle accelerator	376/195
77	⊠		US 5980591 A	19991109		System for processing a plurality of objects contained in a plurality of cassettes	29/25.01
78	⊠		US 5980186 A	19991109	••••••	Fork cover for vertical furnace	414/416.01
79	⊠		US 5956837 A	19990928		Method of detaching object to be processed from electrostatic chuck	29/559
80	⊠		US 5951772 A	19990914		Vacuum processing apparatus	118/723R
81	⊠		US 5950330 A	19990914		Vacuum processing apparatus and operating method therefor	34/406
82	Ø		US 5943531 A	19990824		Electrophotographic apparatus, image forming method, and process for fabricating light receiving member for electrophotography	399/159
83	⊠		US 5936829 A	19990810		electrophotography. Thermally conductive chuck for vacuum processor	361/234
84	⊠		US 5921540 A	19990713		Vacuum corrugation feeder with a retractable corrugator	271/98
85	⊠		US 5915910 A	19990629		Semiconductor wafer transfer method and apparatus	414/331.17

	Current XRef	Retrie	Inventor	S		P	2	3	4	5
64	34/228		Kato, Shigekazu . et al.							
65	414/939		Kirkpatrick, Thomas I.							
66	414/744.2		, et al. Azumano, Hidehito							
<u> </u>	; 414/939		, et al. Kato, Shigekazu		-	ļ	ऻ——			-
67	440/72255		, et al.							
68	118/723FE ; 118/723FI ; 204/298.02 ; 204/298.04 ; 204/298.17 ; 204/298.41 ; 335/209 ; 335/213 ; 335/282 ; 335/297 ; 335/299 ; 335/306		Moslehi, Mehrdad M. , et al.							
69	204/192.2 ; 204/192.22 ; 427/255.32 ; 427/255.36		Yuuki, Akimasa , et al.							
70	95/47 ; 96/10 ; 96/6 ; 96/8		Hasebe, Keizo , et al.							
71			Takahashi, Kazuo							
72	118/500 ; 156/345 ; 279/128 ; 361/234		lwabuchi, Katsuhiko							
73	118/723VE ; 204/298.04		Sakemi, Toshiyuki , et al.							
74	34/210		White, John M. . et al.							
75			Kato, Shigekazu . et al.							
76			Welch, Michael J. , et al.							
77	700/101 ; 700/116 ; 700/121 ; 700/217 ; 700/219 ; 700/226 ; 700/96		Akimoto, Masami , et al.							
78	414/785 ; 414/937		Cheng, Wei Hua							
79	269/8 ; 279/128 ; 29/825 ; 361/234		Shiota, Iku , et al.							
80	118/724 ; 134/1.1 ; 156/345		Matsuse, Kimihiro , et al.							
81			Kato, Shigekazu , et al.							
82	399/350 ; 430/125 ; 430/56		Takai, Yasuyoshi , et al.							
83	279/128		Moslehi, Mehrdad M.							
84	271/104 ; 271/105	•	Acquaviva, Thomas , et al.							
85	414/416.03 ; 414/752.1 ; 414/763 ; 414/773 ; 414/811 ; 414/936 ; 414/937		Howells, John , et al.							
	; 414/941									

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86	⊠		US 5906262 A	19990525		Positioning control system for a non-contacting magnetic conveyor system	198/341.02
87	⊠		US 5900065 A	19990504		Apparatus for the plasma-chemical deposition of polycrystalline diamond	118/723HC
88	⊠		US 5878943 A	19990309		Method of fabricating an electronic circuit device and apparatus for	228/205
89	⊠		US 5872051 A	19990216		performing.the.method Process for transferring material to semiconductor chip conductive pads using.a.transfer.substrate	438/616
90	⊠		US 5863338 A	19990126		Apparatus and method for forming thin film	118/719
91	⊠		US 5849087 A	19981215		Vacuum treatment system for applying thin layers to substrates such as headlights reflectors	118/719
92	×	Ø	US 5829939 A	19981103		Treatment apparatus	414/411
93	Ø		US 5827558 A	19981027		Composite shrimp products and method of making the same	426/274
94	⊠		US 5822389 A	19981013		Alignment apparatus and SOR X-ray exposure apparatus having same	378/34
95	⊠		US 5811316 A	19980922		Method of forming teos oxide and silicon nitride passivation layer on	438/688
96	Ø		US 5810930 A	19980922		aluminum wiring Photo-chemical vapor deposition apparatus having exchange apparatus of optical window and method of exchanging optical window therewith	118/719
97	⊠		US 5803932 A	19980908		Resist processing apparatus having an interface section including two	29/25.01
98	×		US 5785796 A	19980728		stacked substrate waiting tables Vacuum processing apparatus, vacuum processing method, and method for cleaning the vacuum processing apparatus	156/345
99	⊠		US 5784799 A	19980728		Vacuum processing apparatus for substate wafers	34/92
100	⊠		US 5780882 A	19980714		Semiconductor integrated circuit device, process for fabricating the	257/203
101	⊠		US 5776254 A	19980707		same, and apparatus for fabricating the same Apparatus for forming thin film by chemical vapor deposition	118/725
102	⊠		US 5746562 A	19980505		Processing system and device manufacturing method using the same	414/217
103	⊠		US 5739589 A	19980414	,	Semiconductor integrated circuit device process for fabricating the same and apparatus for fabricating the same	257/763
104	×		US 5723360 A	19980303		Method of processing an epitaxial wafer of InP or the like	438/41

	Current XRef	Retrie Classif	Inventor	S	Р	2	3	4	5
86	198/464.3 ; 198/465.2 ; 198/502.3 ; 198/619		Miki, Hiroshi						
87	118/719 ; 118/723MW ; 156/345		Liehr, Michael , et al.						
88	228/180.22 ; 228/207		Nishikawa, Toru , et al.	- 🗆					
89	228/180.22		Fallon, Kenneth Michael , et al.						
90	118/320 ; 118/724 ; 118/725 ; 118/729		Yamada, Yuichiro , et al.						
91	118/733 ; 204/298.25		Kloberdanz, Hermann , et al.						
92	414/416.01 ; 414/937 ; 414/940		lwai, Hiroyuki , et al.						
93	426/643		Corser, Michael Francis , et al.						
94	378/210		Uzawa, Shunichi , et al.						
95	438/788		Sugiura, Jun , et al.						
96	118/715 ; 118/722 ; 414/221		Eom, Young Chang , et al.						
97	118/500		Akimoto, Masami , et al.						
98	118/715 ; 118/719 ; 134/1.1 ; 134/1.2 ; 134/1.3 ; 204/298.25 ; 204/298.32 ; 204/298.33 ; 204/298.35 ; 216/59 ; 216/63 ; 216/67 ; 438/905		Lee, Hideki						
99	414/217 ; 414/416.03 ; 414/937 ; 414/939 ; 414/940		Kato, Shigekazu , et al.						
100	257/206 ; 257/900 ; 438/163		Sugiura, Jun , et al.						
101	118/715 ; 118/726 ; 118/729		Yuuki, Akimasa , et al.						
102	248/638 ; 248/639		Hasegawa, Takayuki , et al.						
103	257/770 ; 257/775		Sugiura, Jun , et al.						
104	117/93 ; 117/97 ; 438/40 ; 438/44 ; 438/46		lwasaki, Takashi						

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	U		Document ID	Sue Date	rayes	Title U	ourient OK
105	⊠		US 5685684 A	19971111		Vacuum processing system	414/217
106	⊠		US 5670286 A	19970923		Electrophotographic light receiving member having an outermost surface with a specific metal element-bearing region and a region substantially free of said metal element which are	430/66
107	⊠		US 5665200 A	19970909		two-dimensionally distributed Substrate processing method and substrate processing apparatus	438/694
108	☒		US 5662469 A	19970902		Heat treatment method	432/6
109	⊠		US 5661913 A	19970902		Vacuum processing apparatus and operating method therefor	34/406
110	×		US 5651868 A	19970729		Method and apparatus for coating thin film data storage disks	204/298.25
111	Ø		US 5651670 A	19970729		Heat treatment method and apparatus thereof	432/5
112	⊠		US 5647945 A	19970715		Vacuum processing apparatus	156/345
113	⋈		US 5641054 A	19970624		Magnetic levitation conveyor apparatus	198/619
114			US 5616208 A	19970401		Vacuum processing apparatus, vacuum processing method, and method for cleaning the vacuum processing apparatus	156/345
115	Ø		US 5580420 A	19961203		Plasma generating method and apparatus and plasma processing method and	216/69
116	⊠		US 5575853 A	19961119		apparatus Vacuum exhaust system for processing apparatus	118/708
117	☒		US 5571366 A	19961105		Plasma processing apparatus	156/345
118	⊠		US 5562383 A	19961008		Treatment apparatus	414/217.1
119	⊠		US 5561021 A	19961001		Electrophotographic photosensitive member having a metal oxide material layer with an improved water repellency formed on the surface of a	430/130
120	⊠		US 5558736 A	19960924		light receiving layer Electron cyclotron resonance apparatus	156/345
121	×		US 5557147 A	19960917		Semiconductor integrated circuit device, process for fabricating the same, and apparatus for fabricating the same	257/763

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<u> </u>	Current XRef 118/719	Retrie Classif	Inventor	S	Р	2	3	4	5
105	; 414/416.03 ; 414/937 ; 414/939 ; 414/940		Kato, Shigekazu , et al.						
106	399/159 ; 430/57.4 ; 430/63		Takei, Tetsuya , et al.						
107	156/345 ; 216/92 ; 430/117 ; 430/323		Fujimoto, Akihiro , et al.						
108	432/11 ; 432/241		Okase, Wataru , et al.						
109	134/902		Kato, Shigekazu , et al.						
110	118/50 ; 118/50.1 ; 118/719 ; 204/298.07 ; 204/298.15 ; 204/298.26 ; 204/298.35		Canady, Mickey Lynn , et al.						
111	432/11 ; 432/241 ; 432/6		Okase, Wataru , et al.						
112	216/67 ; 438/905 ; 438/935		Matsuse, Kimihiro , et al.						
113	104/284 ; 104/292 ; 198/465.1		Mori, Satoshi , et al.						
114	118/715 ; 134/1.1 ; 134/1.2 ; 134/1.3 ; 204/298.25 ; 204/298.32 ; 204/298.33 ; 204/298.35 ; 216/59 ; 216/63 ; 216/67 ; 438/905		Lee, Hideki						
115	156/345 ; 216/70 ; 438/726 ; 438/728		Watanabe, Katsuya , et al.						
116	118/712 ; 118/715 ; 118/725		Arami, Junichi , et al.						
117	118/723 ; 216/59 ; 216/60 ; 216/61 ; 216/68 ; 438/9		Ishii, Nobuo , et al.						
118	118/719 ; 414/411 ; 414/937 ; 414/939 ; 414/940		Iwai, Hiroyuki , et al.						
119	430/132 ; 430/66 ; 430/67		Yamazaki, Koji , et al.						
120	118/723MA ; 118/723MR ; 118/724		Lee, Sang Y. , et al.						
121	257/764 ; 257/770		Sugiura, Jun , et al.						

	I	_	D	D-4- 1	0		Current OD
122	υ ⊠	1	Document ID US 5556500 A	19960917	Pages	Title Plasma etching apparatus	Current OR 156/345
122	Δ.			19900917		riasina etcining apparatus	130/343
123	⋈		US 5553396 A	19960910		Vacuum processing apparatus and operating method therefor	34/406
124	⊠		US 5540152 A	19960730		Delivery conveyor with control window ventilation and extraction system	101/483
125	⋈		US 5529657 A	19960625		Plasma processing apparatus	156/345
126	☒		US 5524131 A	19960604		Alignment apparatus and SOR x-ray exposure apparatus having same	378/34
127	Ø		US 5511005 A	19960423		Wafer handling and processing system	702/84
128	⊠		US 5501739 A	19960326		Apparatus and method for forming thin film	118/719
129	⊠		US 5478195 A	19951226		Process and apparatus for transferring an object and for processing	414/805
130	⊠		US 5476798 A	19951219		Semiconductor wafers Plasma deposition process with substrate temperature control	438/96
131	⊠		US 5457896 A	19951017		Vacuum processing apparatus and operating method therefor	34/406
132	☒		US 5433995 A	19950718		Carbon fiber-reinforced composite heat reflectors	428/300.7
133	⊠		US 5429729 A	19950704	-	Sputtering apparatus, device for exchanging target and method for the	204/192.12
134	⊠		US 5429498 A	19950704		Heat treatment method and apparatus thereof	432/152
135	Ø		US 5425611 A	19950620		Substrate handling and processing system	414/217
136	⊠		US 5382311 A	19950117		Stage having electrostatic chuck and plasma processing apparatus using	156/345
137	Ø		US 5372648 A	19941213		Plasma CVD system	118/723E
138	Ø		US 5357115 A	19941018	***************************************	Processing method for wafers	250/442.11
139	Ø		US 5356092 A	19941018	***************************************	Reduced size tape loading module	242/523
140	☒		US 5349762 A	19940927		Vacuum processing apparatus and operating method therefor	34/406
141	×		US 5346853 A	19940913		Microwave energized deposition process with substrate temperature control for the fabrication of P-I-N photovoltaic	438/97
142	⋈		US 5344720 A	19940906		devices Bistable magneto-optic single crystal films and method of producing same utilizing controlled defect introduction	428/692
143	×		US 5340401 A	19940823		Diamond deposition cell	118/725

	Current XRef	Retrie lassif	Inventor	S	U	Р	2	3	4	5
122	216/71 ; 438/720 ; 438/721		Hasegawa, Makoto , et al.							
123	134/902 ; 34/92 ; 414/222.13		Kato, Shigekazu , et al.							
124	101/240 ; 101/419 ; 101/424.1 ; 34/611 ; 34/88		DeMoore, Howard W.							
125	118/723E ; 118/723I ; 216/68		Ishii, Nobuo							
126	378/160		Uzawa, Shunichi , et al.							
127	324/719 ; 324/765 ; 700/213		Abbe, Robert C. , et al.							
128	118/715 ; 118/725 ; 118/726 ; 118/729		Yamada, Yuichiro , et al.							
129	250/441.11 ; 414/217 ; 414/937 ; 414/939		Usami, Yasutsugu							
130	136/258 ; 427/574 ; 427/575 ; 427/578 ; 430/65 ; 438/485		Guha, Subhendu							
131	34/92		Kato, Shigekazu , et al.							
132	428/408		Matthews, Linn H. , et al.							
133	204/298.09 ; 204/298.19 ; 204/298.22 ; 204/298.26		Kamei, Mitsuhiro , et al.							
134	432/241 ; 432/253 ; 432/5 ; 432/6		Okase, Wataru , et al.							
135	118/719 ; 204/298.25 ; 414/416.05 ; 414/416.09 ; 414/938 ; 414/939 ; 414/940		Hughes, John L. , et al.							
136	118/723E ; 118/728		Ishikawa, Kenji , et al.							
137	118/719 ; 118/725 ; 118/729		Yamamoto, Shigeyuki , et al.							
138	250/492.21		Asakawa, Teruo , et al.							
139	156/502		Perego, Luciano Kato, Shigekazu							
140	34/92		, et al.							
141	136/258 ; 438/485 ; 438/488		Guha, Subhendu , et al.							
142	427/127 ; 427/129 ; 427/130 ; 428/694GT ; 428/694ML ; 428/702 ; 430/945		Belt, Roger F. , et al.							
143	118/724 ; 118/726 ; 423/446 ; 427/249.11 ; 427/577		Cann, Gordon L.							

	U	1	Document ID	ue Date	Pages	Title	Current OR
144	×		US 5336029 A	19940809		Loading apparatus having a suction-hold mechanism	414/217
145	⊠		US 5331191 A	19940719		Semiconductor integrated circuit device, process for fabricating the	257/336
146	⊠		US 5329733 A	19940719		same, and apparatus for fabricating the same. Wafer slicing and grinding machine and a method of slicing and grinding	451/10
147	⊠		US 5324087 A	19940628		wafers Sucked substrate detecting apparatus	294/64.1
148	☒		US 5314509 A	19940524		Vacuum processing apparatus and operating method therefor	34/406
149	⊠		US 5310453 A	19940510		Plasma process method using an electrostatic chuck	438/716
150	⊠		US 5296036 A	19940322		Apparatus for continuously forming a large area functional deposit film including microwave transmissive member transfer mean	118/718
151			US 5292388 A	19940308		Conveyorized vacuum applicator and method therefor	156/64
152	⊠		US 5290417 A	19940301		Apparatus with axial gas distribution for vacuum coating substrates on a carousel	204/298.25
153	Ø		US 5286296 A	19940215		Multi-chamber wafer process equipment having plural, physically communicating transfer means	118/719
154	⊠		US 5284411 A	19940208	***************************************	Conveyor for conveying workpieces in a vacuum chamber	414/217
155	⊠		US 5281320 A	19940125		Wafer coating system	204/298.15
156	⊠		US 5275184 A	19940104		Apparatus and system for treating surface of a wafer by dipping the same in a treatment solution and a gate device for chemical agent used in	134/57R
157	☒		US 5273423 A	19931228		the apparatus and the system Heat treatment apparatus	432/241

[Current XRef	Retrie	Inventor	s	Р	2	3	4	5
144	118/719 ; 267/136 ; 414/223.02 ; 414/225.01 ; 414/627 ; 414/719 ; 414/736 ; 414/737 ; 901/40		Kato, Naoki , et al.		· 🗆				
145	257/338		Sugiura, Jun , et al.						
146	125/13.02 ; 451/41 ; 451/70		Steere, Jr., Robert E.						
147	294/907		Shimose, Yuichiro , et al.						
148	134/902 ; 34/92		Kato, Shigekazu , et al.						
149	7, 34/92		Fukasawa, Kazuo						
150	118/723ME ; 118/725 ; 118/730 ; 118/733 ; 136/249 ; 136/258 ; 156/345		, et al. Matsuyama, Jinsho , et al.						
151	100/151 ; 100/154 ; 100/222 ; 100/319 ; 100/320 ; 100/325 ; 156/285 ; 156/361 ; 156/368 ; 156/368 ; 156/538 ; 156/538 ; 156/538 ; 156/539 ; 156/580 ; 156/580 ; 156/583,5		Candore, Amedeo						. 🗖
152	118/719 ; 118/730 ; 204/298.07 ; 204/298.28 ; 204/298.35		Zejda,:Jaroslav						
153	118/729 ; 204/298.25 ; 204/298.26 ; 204/298.35 ; 414/217	THE THE PARTY OF T	Sato, Junichi , et al.						
154	198/619 ; 414/935		Enomoto, Yoshihiro , et al.						
155	118/729 ; 118/730 ; 156/345 ; 198/478.1 ; 198/803.8 ; 204/298.25 ; 269/254R ; 414/217		Turner, Frederick T. , et al.						
156	134/102.1 ; 134/105 ; 134/155 ; 134/186 ; 134/902		Nishizawa, Hisao , et al.						
157	414/217 ; 414/937 ; 414/939 ; 414/940 ; 432/152 ; 432/2 ; 432/253		Shiraiwa, Hirotsugu						

	U	1	Document ID	sue Date Pag	ges Title	Current OR
158	⊠		US 5259942 A	19931109	Device for transferring a workpiece into and out from a vacuum chamber	204/298.25
159	⊠		US 5248886 A	19930928	Processing system	250/442.11
160	⊠		US 5244143 A	19930914	Apparatus and method for injection molding solder and applications	228/180.21
161	⊠		US 5217501 A	19930608	thereof Vertical wafer heat treatment apparatus having dual load lock chambers	29/25.01
162	⋈		US 5215420 A	19930601	Substrate handling and processing system	414/217
163	Ø		US 5203547 A	19930420	Vacuum attraction type substrate holding device	269/21
164	⊠		US 5202275 A	19930413	Semiconductor integrated circuit device, process for fabricating the	438/210
165	⊠		US 5189843 A	19930302	same, and apparatus for fabricating the same Wafer slicing and grinding machine and a method of slicing and grinding	451/10
166	⊠		US 5185757 A	19930209	wafers Modularized replaceable vaporizer and extractor apparatus	372/56
167	⊠		US 5182093 A	19930126	Diamond deposition cell	423/446
168	⊠		US 5154730 A	19921013	Semiconductor wafer processing module having an inclined rotating wafer handling turret and a method of using the module	29/25.01
169	⊠		US 5135608 A	19920804	Method of producing semiconductor devices	438/584
170	Ø		US 5121705 A	19920616	Loading lock for chemical vapor deposition apparatus	118/719
171	Ø		US 5112469 A	19920512	Apparatus for the inward and outward transfer of a workpiece in a vacuum chamber	204/298.25
172	⊠		US 5085410 A	19920204	Modular processing system	266/44
173	⊠		US 5040484 A	19910820	Apparatus for retaining wafers	118/503
174	⊠		US 5024747 A	19910618	Wafer coating system	204/298.09

	Current XRef	Retrie Classif	Inventor	s	Р	2	3	4	5
	118/719	Tetrician Glassii	inventor		<u> </u>	-		·	J
158	; 118/730 ; 204/298.28 ; 414/217		Kempf, Stefan						
159	250/492.21		Asakawa, Teruo , et al.						
160	228/253 ; 228/56.3 ; 427/282 ; 427/96		Ference, Thomas G. , et al.						
161	118/50.1 ; 118/719		Fuse, Noboru , et al.						
162	118/719 ; 204/298.25 ; 414/416.05 ; 414/416.09 ; 414/937 ; 414/939		Hughes, John L. , et al.						
163			Marumo, Mitsuji						
164	438/231		Sugiura, Jun , et al.						
165	451/180 ; 451/339 ; 451/70		Steere, Jr., Robert E.						
166			Finch, Lester M.						
167	427/228 ; 427/249.7 ; 427/249.8 ; 427/902		Cann, Gordon L.						
168	118/730 ; 204/298.11 ; 204/298.15 ; 204/298.25 ; 204/298.28		Hodos, Julian , et al.						
169	118/50.1 ; 118/620 ; 118/620 ; 118/728 ; 156/345 ; 204/298.25 ; 204/298.35 ; 414/217 ; 414/937 ; 414/939 ; 414/941 ; 438/653 ; 438/694 ; 438/702 ; 438/704		Okutani, Ken						
170	118/725 ; 118/729 ; 414/217		Sugino, Masao						
171	118/719 ; 118/730 ; 204/298.28 ; 414/217 ; 414/223.01		Kempf, Stefan , et al.						
172	204/157.22 ; 250/281 ; 266/205		Ficnh, Lester M.						
173	118/730 ; 250/442.11 ; 269/238 ; 269/254R ; 279/139		Mears, Eric L. , et al.						
174	118/725 ; 118/729 ; 156/345 ; 165/104.34 ; 198/339.1 ; 198/478.1 ; 198/803.8 ; 204/298.15 ; 204/298.25 ; 269/254R ; 414/217 ; 414/226.05		Turner, Frederick T. , et al.						

			Decument ID	Deta I	Donne	Title	Current OB
175	U ⊠	1	Document ID US 4981408 A	19910101	Pages	Dual track handling and processing system	Current OR 414/217
176	⊠		US 4929139 A	19900529		Passive electrostatic vacuum particle collector	414/217
177	⊠	П	US 4924599 A	19900515		UV curing apparatus	34/278
178			US 4911353 A	19900327		Solar collector having absorber plate formed by spraying molten metal	228/183
179	Ø		US 4909314 A	19900320		Apparatus for thermal treatment of a wafer in an evacuated environment	165/80.3
180	×		US 4853102 A	19890801		Sputtering process and an apparatus for carrying out the same	204/298.06
181	×		US 4834023 A	19890530		Apparatus for forming deposited film	118/730
182	⊠		US 4832809 A	19890523		Process for preparation layered composite constructional material,	204/192.15
183	⊠		US 4817556 A	19890404		especially for sliding and friction members Apparatus for retaining wafers	118/503
184	⊠	_	US 4776745 A	19881011		Substrate handling system	414/217
185	⊠		US 4776744 A	19881011		Systems and methods for wafer handling in semiconductor process equipment	414/217
186	Ø		US 4773944 A	19880927		Large area, low voltage, high current photovoltaic modules and method of fabricating same	136/249
187	⊠		US 4756815 A	19880712		Wafer coating system	204/298.25
188	⊠		US 474 3570 A	19880510		Method of thermal treatment of a wafer in an evacuated environment	165/80.1
189	⊠		US 4693777 A	19870915		Apparatus for producing semiconductor devices	156/345
190	⊠		US 4680061 A	19870714		Method of thermal treatment of a wafer in an evacuated environment	250/398
191	⊠		US 4674621 A	19870623		Substrate processing apparatus	198/378

	Current XRef	Retrie Classif	Inventor	T s		Р	2	3	4	5
175	118/719 ; 414/222.09	Ketile A. Olassii	Hughes, John L.						0	
176	414/937 ; 414/939 ; 55/385.2 ; 96/100 : 96/72		Vorreiter, John W. , et al.							
177	34/518		Bubley, Henry J.	П	-	П				
178	126/634 ; 126/660 ; 126/661 ; 126/908 ; 164/46 ; 165/171 ; 228/203 ; 228/226 ; 228/248.1 ; 228/261		Deakin, David							
179	118/725 ; 204/192.12 ; 204/298.09		Lamont, Jr., Lawrence T.							
180	204/298.16 ; 204/298.25 ; 204/298.37		Tateishi, Hideki , et al.							
181	118/715		Saitoh, Keishi , et al.							
182	204/192.16 ; 204/192.3		Hodes, Erich , et al.							
183	118/730 ; 250/442.11 ; 269/238 ; 269/254R ; 279/130 ; 279/139		Mears, Eric L. , et al.							
184	118/50 ; 118/500 ; 118/729 ; 187/267 ; 414/286 ; 414/416.03 ; 414/609 ; 414/936 ; 414/939		Foley, Michael S.							
185	269/254R ; 269/287 ; 414/416.09 ; 414/806 ; 414/937 ; 414/938 ; 414/940		Stonestreet, Paul , et al.							
186	136/251 ; 136/256 ; 136/258 ; 156/324 ; 438/62 ; 438/66 ; 438/80		Nath, Prem , et al.							
187	204/192.12		Turner, Frederick T. , et al.							
188	148/DIG.83 ; 250/398 ; 250/492.1 ; 438/795		Lamont, Jr., Lawrence T.							
189	118/50 ; 118/728 ; 134/105 ; 134/902 ; 204/298.25 ; 438/716		Hazano, Shigeki , et al.							
190	204/192.12 ; 250/492.1		Lamont, Jr., Lawrence T.							
191	118/503 ; 198/474.1 ; 198/478.1 ; 204/298.25 ; 414/217 ; 414/226.01 ; 414/939		Takahashi, Nobuyuki							

	U	1	Document ID	ue Date	Pages	Title	Current OR
•							
192			US 4643629 A	19870217		Automatic loader	414/331.17
193	⊠		US 4634331 A	19870106		Wafer transfer system	414/217
194	⊠		US 4596385 A	19860624		Top vacuum corrugation feeder with moveable air blocking vane	271/94
195	⊠		US 4589647 A	19860520		Top vacuum corrugation feeder with a valveless feedhead	271/94
196	⊠		US 4589608 A	19860520		Cassette loading apparatus	29/792
197	×		US 4584045 A	19860422		Apparatus for conveying a semiconductor wafer	156/345
198	Ø		US 4557785 A	19851210		Apparatus for wet processing	156/345
199	×		US 4542712 A	19850924	-	Apparatus for molecular beam epitaxy	118/726
200	⊠		US 4526670 A	19850702		Automatically loadable multifaceted electrode with load lock mechanism	204/298.35
201	⊠		US 4523966 A	19850618		Process of producing silicon ribbon with p-n junction	438/490
202	Ø		US 4514130 A	19850430		Substrate elevator mechanisms	414/416.01
203	⋈		US 4513430 A	19850423		Missing or broken wafer sensor	377/39
204	⊠		US 4512527 A	19850423		Cassette loading apparatus	242/527.7
205	⊠		US 4498833 A	19850212		Wafer orientation system	414/217
206	⊠		US 4498832 A	19850212		Workpiece accumulating and transporting apparatus	414/217
207	⊠		US 4465416 A	19840814	-	Wafer handling mechanism	414/217

	Current XRef	Retrie	Inventor	S		P	2	3	4	5
	198/346.2				_					
192	; 198/347.3 ; 204/298.25 ; 414/217 ; 414/416.08 ; 414/757 ; 414/936 ; 414/937 ; 414/939		Takahashi, Nobuyuki , et al.							
193	110/180 ; 118/724 ; 118/728 ; 118/733 ; 204/298.25 ; 432/237		Hertel, Richard J.			0				
194	271/108 ; 271/98		Silverberg, Morton							
195	271/34		Roller, George J.							
196	156/506		Rehklau, George D. , et al.							
197	204/298.35 ; 414/217 ; 414/226.05 ; 414/744.5 ; 414/937 ; 414/939 ; 414/941 ; 438/716		Richards, Edmond A.							
198	134/198 ; 134/33 ; 134/902 ; 216/91 ; 216/92		Ohkuma, Yuji							
199	118/500 ; 118/729 ; 414/217 ; 414/937 ; 414/939		Sato, Kazuo , et al.							
200	118/324 ; 118/50.1 ; 118/719 ; 118/720 ; 156/345 ; 438/716		Hajj, John G.							
201	136/258 ; 264/212 ; 428/620 ; 428/939 ; 438/62		Tsuya, Noboru , et al.							
202	198/465.4 ; 198/468.8 ; 414/938		Gladish, Gary W.							
203	340/674 ; 377/24 ; 377/8		Vora, Mahasukh , et al.							
204	156/506 ; 242/532.1 ; 242/533.1 ; 242/534 ; 242/908 ; 242/909		Rehklau, George D. , et al.							
205	118/729 ; 118/730 ; 250/492.2 ; 414/222.02 ; 414/416.09 ; 414/936 ; 414/938 ; 414/939		Hertel, Richard J.							
206	414/935 ; 414/937 ; 414/939		Corville, Richard E.							
207	118/50 ; 118/719 ; 118/729 ; 198/346.2 ; 198/468.6 ; 204/298.25 ; 414/939 ; 414/941		Burkhalter, David W. , et al.							

	U	1	Document ID	ue Date	Pages	Title	Current OR
	U	1	Document ID	sue Date	Pages	Title	Current OR
208	⊠		US 4449885 A	19840522		Wafer transfer system	414/416.08
209	Ø		US 4431473 A	19840214		RIE Apparatus utilizing a shielded magnetron to enhance etching	156/345
210	⋈		US 4405435 A	19830920		Apparatus for performing continuous treatment in vacuum	204/298.25
211	⊠		US 4378189 A	19830329		Wafer loading device	118/500
212	⋈		US 4358472 A	19821109		Multi-layer coating method	427/10
213			US 4313783 A	19820202		Computer controlled system for processing semiconductor wafers	438/716
214	☒		US 4276325 A	19810630		Method for supporting flexible sheet while applying graded shade band thereon.	427/468
215	☒		US 4254735 A	19810310 · -		Apparatus for supporting flexible sheet while applying graded shade band thereon	118/700
216	☒		US 4239016 A	19801216		Apparatus for handling flexible sheet while applying graded shade band thereon.	118/624
217	⊠		US 4227922 A	19801014	***************************************	Material separation	75/10.67
218	Ø		US 4208159 A	19800617		Apparatus for the treatment of a wafer by plasma reaction	414/223.02
219	Ø		US 4188770 A	19800219		Machine for packaging various articles	53/509
220	☒		US 4118116 A	19781003		X-ray processing system	378/28
221	☒		US 4080053 A	19780321		Transfer apparatus and method	399/317
222	⊠		US 4066801 A	19780103		Continuous system for providing a catalytic coating on support members	427/8
223	×		US 4047624 A	19770913		Workpiece handling system for vacuum processing	414/217
224	⊠		US 4039482 A	19770802		Method of coating and impregnating catalyst support members	502/332

	Current XRef	Retrie Classif	Inventor	s	Р	2	3	4	5
	198/346.2	Retrieva Classii	Inventor	3	<u> </u>			-	-
208	; 414/416.09 ; 414/936 ; 414/938 ; 414/939 ; 414/940		Hertel, Richard J. , et al.						
209	204/192.32 ; 204/298.37 ; 438/732		Okano, Haruo , et al.						
210	118/719 ; 414/217 ; 414/416.03 ; 414/937 ; 414/939		Tateishi, Hideki , et al.						
211	118/730 ; 414/737 ; 414/937		Takeshita, Osamu , et al.						
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220	198/726 ; 198/867.11		Koontz, Paul G. , et al.						
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223	118/719 ; 118/729 ; 118/733 ; 414/287 ; 414/935 ; 414/939		Dorenbos, Frederick William						
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